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A							A
	PCB Number: TIDA-00598						
	PCB Rev: E1						
	DNP DNP DNP						
	FID1 FID2 FID3						
	PCB LOGO						
	Pb-Free Symbol						
	PCB LOGO						
	LOGO Texas Instruments						
	Label Table	7	6091 VIN	VOUT_3V3	VOLT 2V2		
	Variant Label Text		VIN O U1		VOUT_3V3	VOUT_1V8	
в	001 TIDA-00598	_		OUT A2 108-0907-001 108-0907-001 1µF		- C4	в
		_			C3 1µF LP5900TL-1.8/NOPB	1µF	
		-		GND			
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		_				VOUT_1V8	
\square						VOUT_1V8	H
	ZZ2 Assembly Note These assemblies are ESD sensitive, ESD precautio	nns shall be observed				108-0907-001 VOUT_1V8	
			GND				
		and all contaminants. Use of no clean flux is not acceptable.					
	ZZ4 Assembly Note These scampbing must comply with workmonship of	tandards IPC-A-610 Class 2, unless otherwise specified.					
c	mese assemblies must comply with workmanship si	nandarus in 0.440 to Class 2, unless otherwise specified.					c
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		Tayae Instruments and/or the licenses	s do not warrant the accuracy or completeness of this specification	or any information contained therein. Taxas Instruments and/or i	TID #: 00598 Project Title:Power Refe Number: TIDA-00598 Rev: E1 Sheet Title: Small size p SN/DERV: Version control diseled Assembly Version	rence Delsgn for CC256X Bluetooth Controller Sheet:1 of 1	s
		warrant that this design will meet the licensors do not warrant that the desi	specifications, will be suitable for your application or fit for any part ign is production worthy. You should completely validate and test you	icular purpose, or will operate in an implementation. Texas Instruments alloyof our design implementation to confirm the system functionality for several sectors and the system functional sectors and the system functionality for several sectors and the system functional sectors and the system functionality for several sectors an	Orderable: IV/A Designed for:Public Rel TID #: 00598 Project Title: Power Ref Number: TIDA-00598 Rev: E1 Shett Title: Shett	I.~(6).SchDoc Size: B http://www.ti.com m/support © Texas Instruments 2015	
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